Objects of the ~~invention~~disclosure

One of the objects of the present ~~invention~~disclosure was to provide a CMP composition and a CMP process appropriate for the chemical-mechanical polishing of III-V materials, particularly GaAs substrates, and showing an improved polishing performance, especially

(i) a high material removal rate (MRR) of the III-V material, for example GaAs,
(ii) a low static etch rate (SER) of the III-V material, for example GaAs,
(iii) high surface quality of the III-V material, for example GaAs, after the CMP step,
(iv) safe handling and reduction of hazardous by-products – for example the toxic gas AsH_3 in case of GaAs polishing – to a minimum, or
(v) or the combination of (i), (ii), (iii) and (iv).

Moreover, a CMP process was sought that is easy to apply and requires as few steps as possible.

Summary ~~of the invention~~

~~Accordingly,~~ There is provided a process for the manufacture of semiconductor devices comprising the chemical-mechanical polishing of a substrate or layer containing at least one III-V material in the presence of a CMP composition (Q1) comprising

(A) inorganic particles, organic particles, or a mixture or composite thereof,
(B) at least one type of a polymer comprising at least one *N*-heterocycle, and
(M) an aqueous medium

and whereas Q1 has a pH of from 1.5 to 4.5~~,~~
~~was found~~.

In a first aspect, there is provided a process for the manufacture of semiconductor devices comprising the chemical-mechanical polishing of III-V materials

in the presence of a chemical-mechanical polishing composition (Q1) comprising
(A) inorganic particles, organic particles, or a mixture or composite thereof,
(B) a polymer comprising at least one *N*-heterocycle, and
(M) an aqueous medium
and whereas Q1 has a pH of from 1.5 to 4.5.

Moreover, the use of the CMP composition (Q1) for chemical-mechanical polishing of a substrate or layer containing at least one III-V material was found.

In a second aspect, there is provided the use of the chemical-mechanical polishing composition (Q1) comprising

(A) inorganic particles, organic particles, or a mixture or composite thereof,
(B) at least one type of a polymer comprising at least one *N*-heterocycle, and
(M) an aqueous medium
and whereas Q1 has a pH of from 1.5 to 4.5

for chemical-mechanical polishing of a substrate or layer containing at least one III-V material.

~~On the other hand,~~In a third aspect, there is provided a process for the manufacture of semiconductor devices comprising the chemical-mechanical polishing of a substrate or layer containing at least one III-V material in the presence of a chemical-mechanical polishing composition (Q2) comprising

(A) inorganic particles selected from the group consisting of alumina, ceria, copper oxide, iron oxide, nickel oxide, manganese oxide, silica, silicon nitride, silicon carbide, tin oxide, titania, titanium carbide, tungsten oxide, yttrium oxide and zirconia, or organic particles, or a mixture or composite thereof,

(C) a non-polymeric compound comprising at least one *N*-heterocycle, and

(M) an aqueous medium

and whereas Q2 has a pH of from 1.5 to 4.5~~;~~

~~was found~~.

Furthermore, the use of the CMP composition (Q2) for chemical-mechanical polishing of a substrate or layer containing at least one III-V material was found.

In a fourth aspect, there is provided the use of the chemical-mechanical polishing composition (Q2) comprising

(A) inorganic particles selected from the group consisting of alumina, ceria, copper oxide, iron oxide, nickel oxide, manganese oxide, silica, silicon nitride, silicon carbide, tin oxide, titania, titanium carbide, tungsten oxide, yttrium oxide and zirconia, or organic particles, or a mixture or composite thereof,

(C) a non-polymeric compound comprising at least one *N*-heterocycle, and

(M) an aqueous medium

and whereas Q2 has a pH of from 1.5 to 4.5

for chemical-mechanical polishing of a substrate or layer containing at least one III-V material.